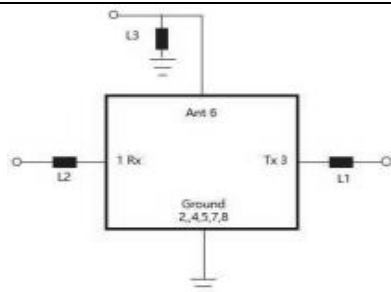


	4905-5845	dB	12	16	-
Attenuation (2110-2170)	1-1920	dB	35	44	-
	190	dB	50	76	-
	718-748	dB	45	55	-
	814-849	dB	45	53	-
	880-915	dB	45	51	-
	1427-1447	dB	40	45	-
	1447-1463	dB	40	45	-
	1730-1790	dB	42	46	-
	1710-1785	dB	39	44	-
	1920-1980	dB	47	53	-
	1980-2015	dB	35	43	-
	2015-2075	dB	9	15	-
	2255-6130	dB	36	43	-
	2400-2500	dB	40	48	-
	2500-2570	dB	40	47	-
	4030-4150	dB	40	46	-
	4220-4340	dB	40	45	-
	4900-5950	dB	37	43	-
Isolation	1920-1980	dB	50	53	-
	2110-2170	dB	51	54	-
Operation Temperature	-20°C~+85°C	°C	-	-	-
Storage Temperature	-40°C~+85°C	°C	-	-	-
RF Power Dissipation	+29	dBm	-	-	-
Remark	Note 1: Test Temperature: 25°C±2°C Note 2: Terminating source impedance: 50Ω. Terminating load impedance: 50Ω				

(3)Test Circuit



Port	Matching Component
Tx	L1 : 1.5 nH (Ideal inductor)
Rx	L2 : 1.6 nH (Ideal inductor)
Ant	L3 : 3.0 nH (Ideal inductor)

Figure 1 Electrical Characteristics: Tx to Ant.

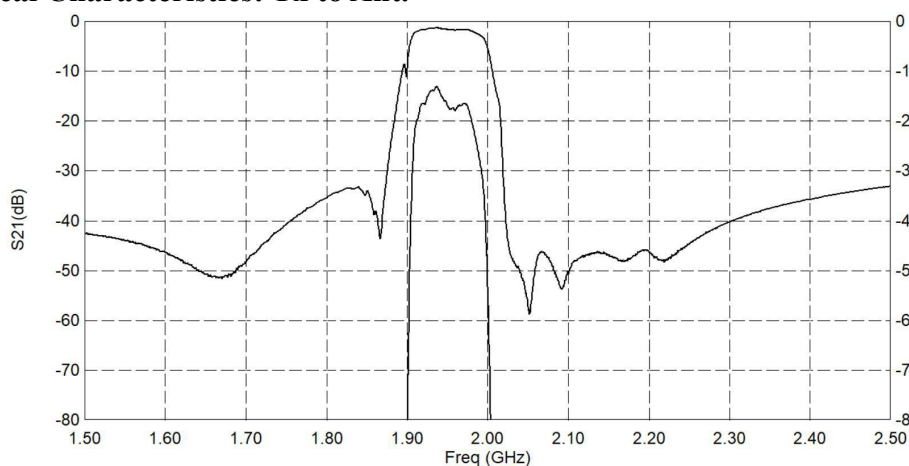


Figure 2 Electrical Characteristics: Tx to Ant.

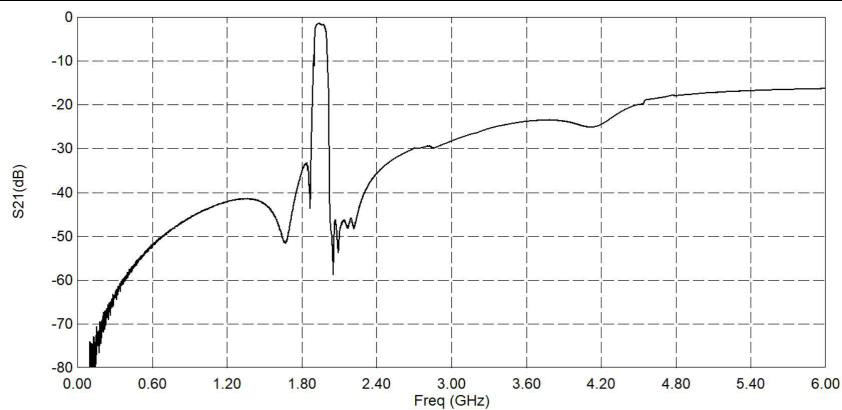


Figure 3 Electrical Characteristics: Ant to Rx.

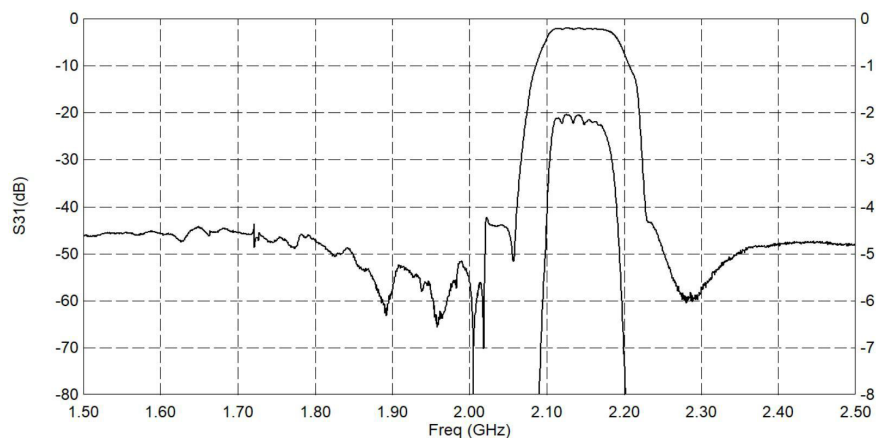


Figure 4 Electrical Characteristics: Ant to Rx.

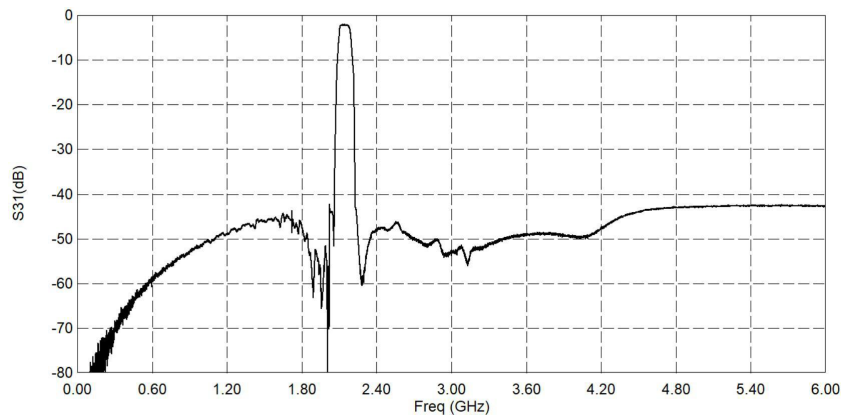


Figure 5 Electrical Characteristics: Tx to Rx.

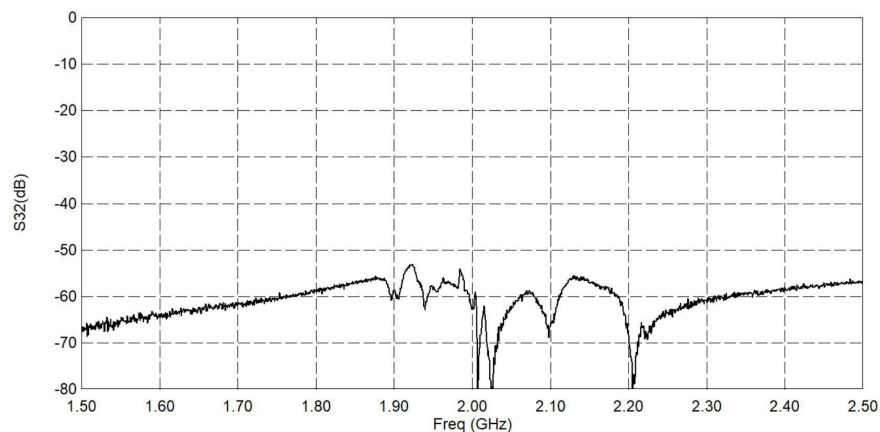
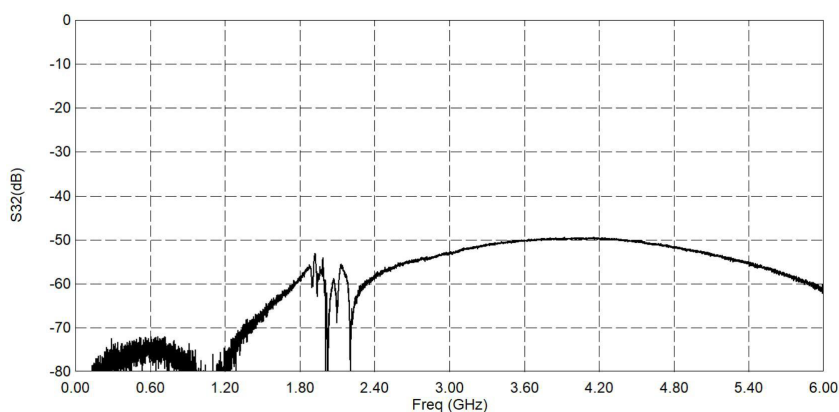
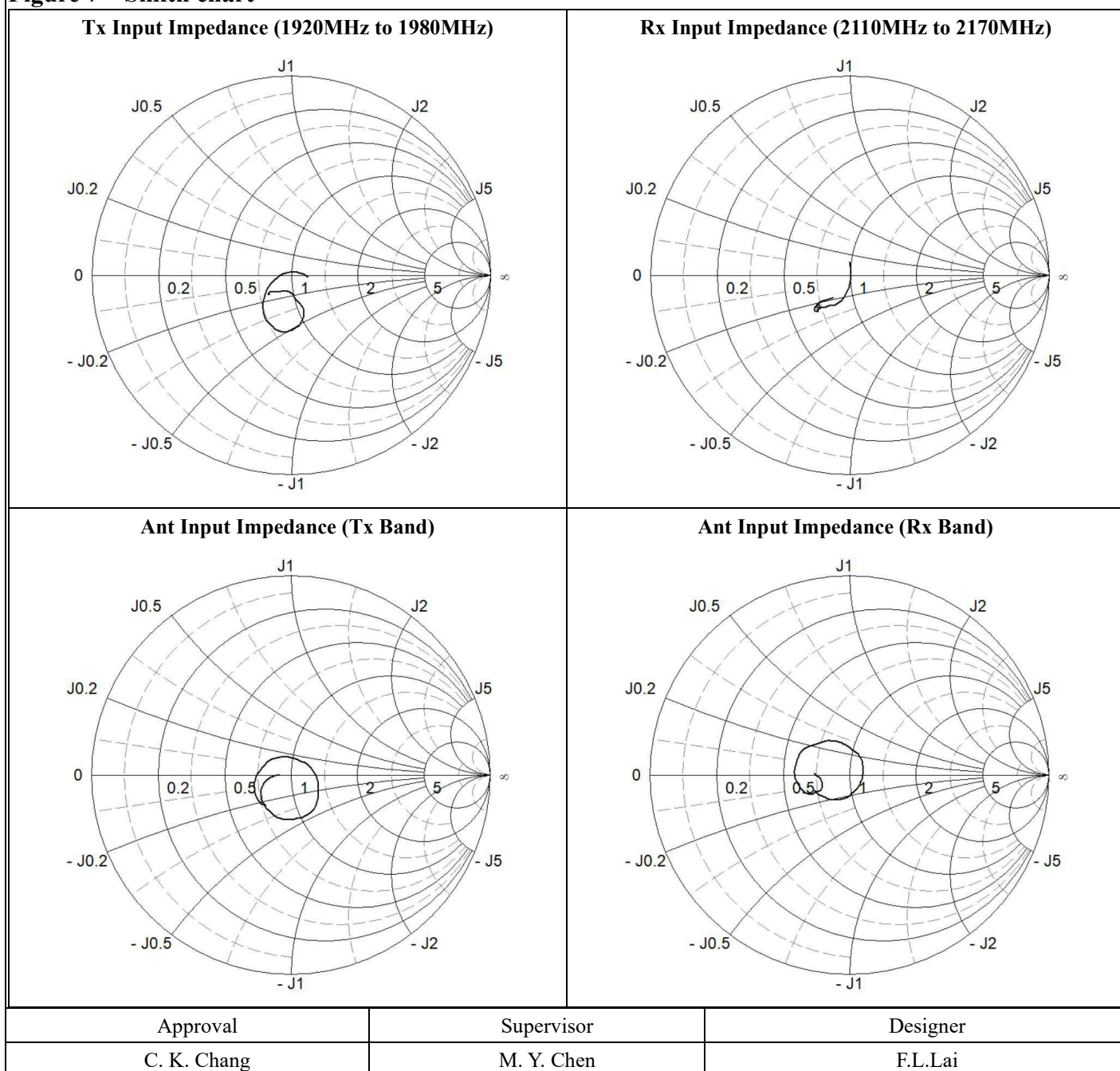
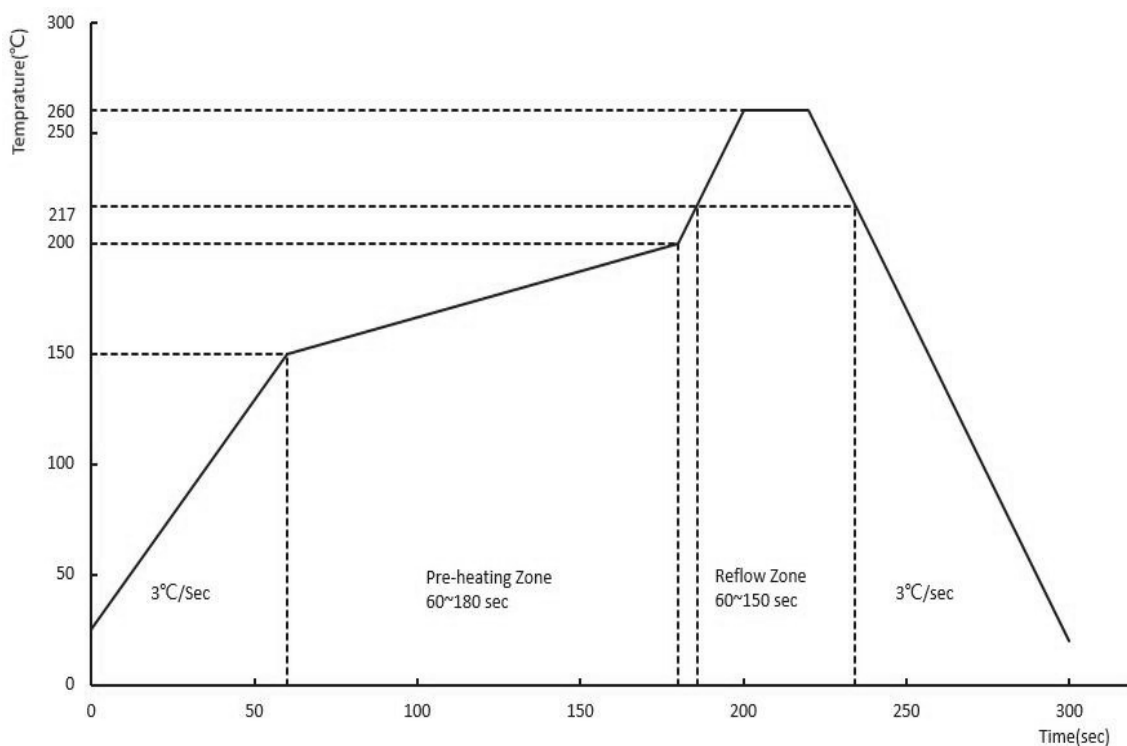


Figure 6 Electrical Characteristics: Tx to Rx.

Figure 7 Smith chart


Recommended SMT Solder Profile



Reliability

No.	Test item	Test condition	
1	Temperature Storage	Temperature: 85°C±2°C , Duration: 250h , Recovery time: 2h±0.5h Temperature: -40°C±3°C , Duration: 250h ,Recovery time: 2h±0.5h	
2	Humidity Test	Conditions: 60°C±2°C ,90~95%RH	Duration:250h
3	Thermal Shock	Heat cycle conditions: TA=-40°C±3°C, TB=85°C±2°C, t1=t2=30min, Switch time: ≤3min, Cycle time: 100 times, Recovery time: 2h±0.5h.	
4	Vibration Fatigue	Frequency of vibration:10~55Hz Directions: X,Y and Z	Amplitude:1.5mm Duration: 2h
5	Drop Test	Cycle time:10times	Height:1.0m
6	Solder Ability Test	Temperature:245°C±5°C Depth: DIP--2/3, SMD--1/5	Duration:3.0s--5.0s
7	Resistance to Soldering Heat	Thickness of PCB:1mm , Solder condition: 260°C±5°C , Duration:10±1s Temperature of Soldering Iron: 350°C±10°C, Duration: 3~4s, Recovery time : 2 ± 0.5h	